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(12) **United States Design Patent** (10) **Patent No.:** **US D1,089,089 S**
Sakurai et al. (45) **Date of Patent:** **** Aug. 19, 2025**

(54) **LIGHT-EMITTING ELEMENT MODULE**

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(**) Term: **15 Years**

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(51) **LOC (15) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**
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D26/120

CPC H01L 33/04; H01L 33/08; H01L 33/10;
H01L 33/20; H01L 33/38; H01L 33/42;
H01L 25/167; H01L 25/0753; H01L
27/15; H01L 27/156; H01L 27/0248;
F21S 43/00; G02B 6/0028

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a light-emitting element module
as shown and described.

DESCRIPTION

FIG. 1 is a front view of a light-emitting element module of
the present invention;

FIG. 2 is a rear view thereof;

FIG. 3 is a top plan view thereof;

FIG. 4 is a bottom plan view thereof;

FIG. 5 is a right side view thereof;

FIG. 6 is a left side view thereof;

FIG. 7 is a front, top and right side perspective view thereof;

FIG. 8 is a rear, bottom and left side perspective view
thereof;

FIG. 9 is a sectional view thereof with inner mechanism is
omitted taken along the line 9-9 in FIG. 3;

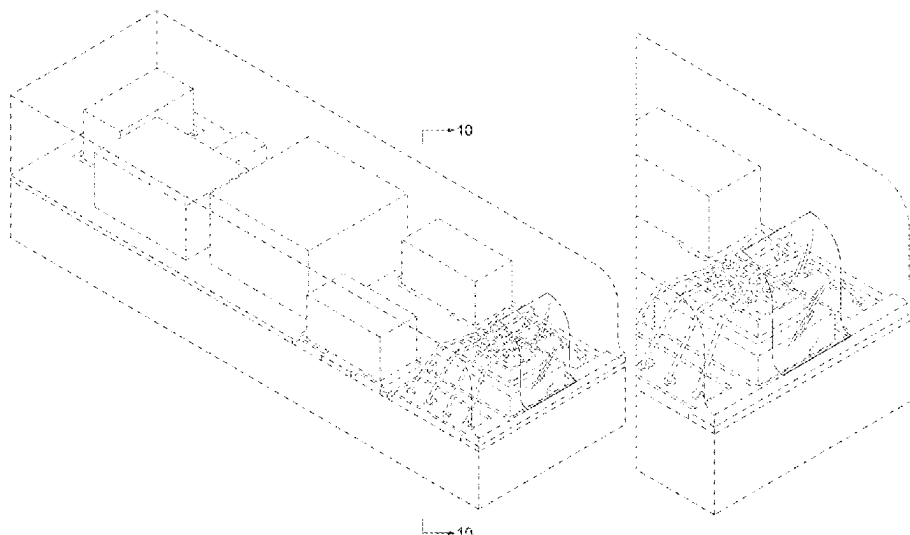
FIG. 10 is an enlarged view thereof defined by the line 10-10
in FIG. 7; and,

FIG. 11 is an enlarged sectional view thereof with inner
mechanism is omitted defined by the line 11-11 in FIG. 9.

The broken lines show portions of a light-emitting element
module that form no part of the claimed design.

The alternate long and short dash lines define the bounds of
the claimed design and form no part thereof.

1 Claim, 11 Drawing Sheets



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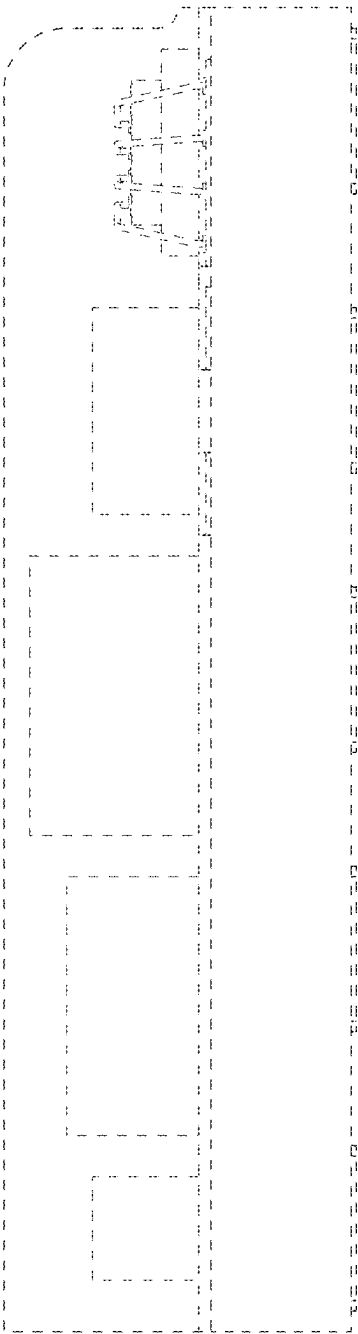


FIG. 1

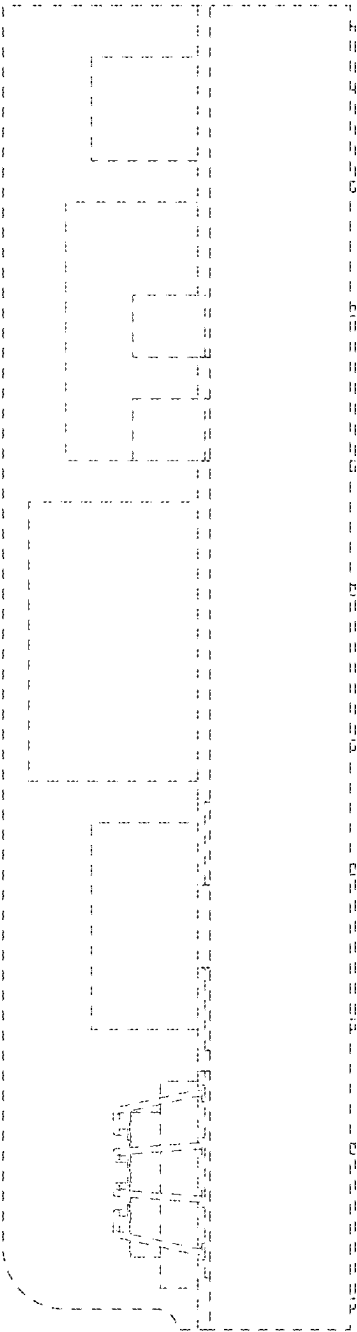


FIG. 2

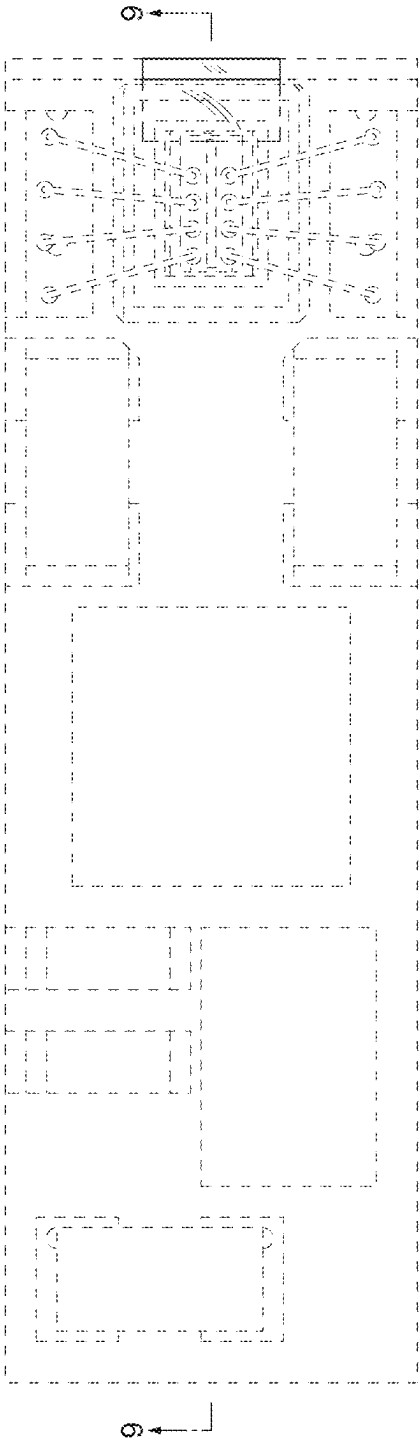


FIG. 3

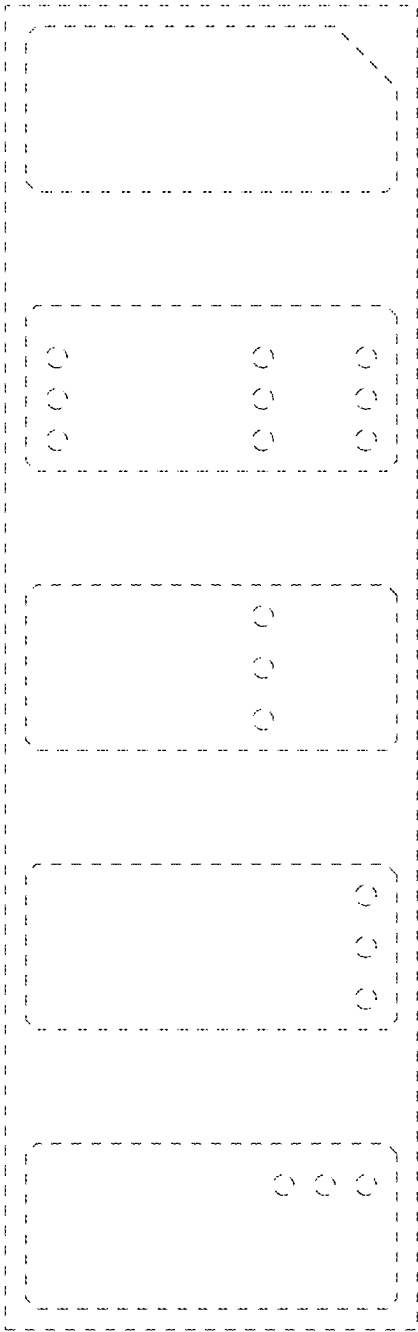


FIG. 4

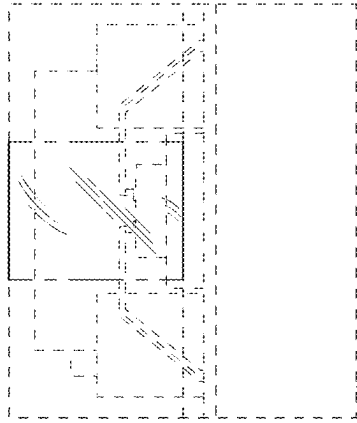


FIG. 5

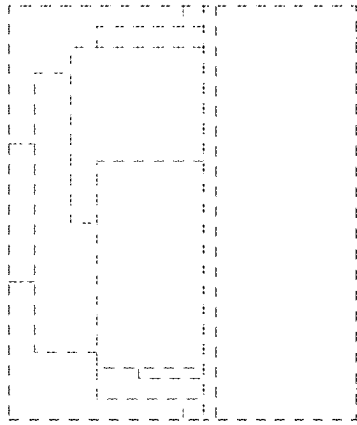


FIG. 6

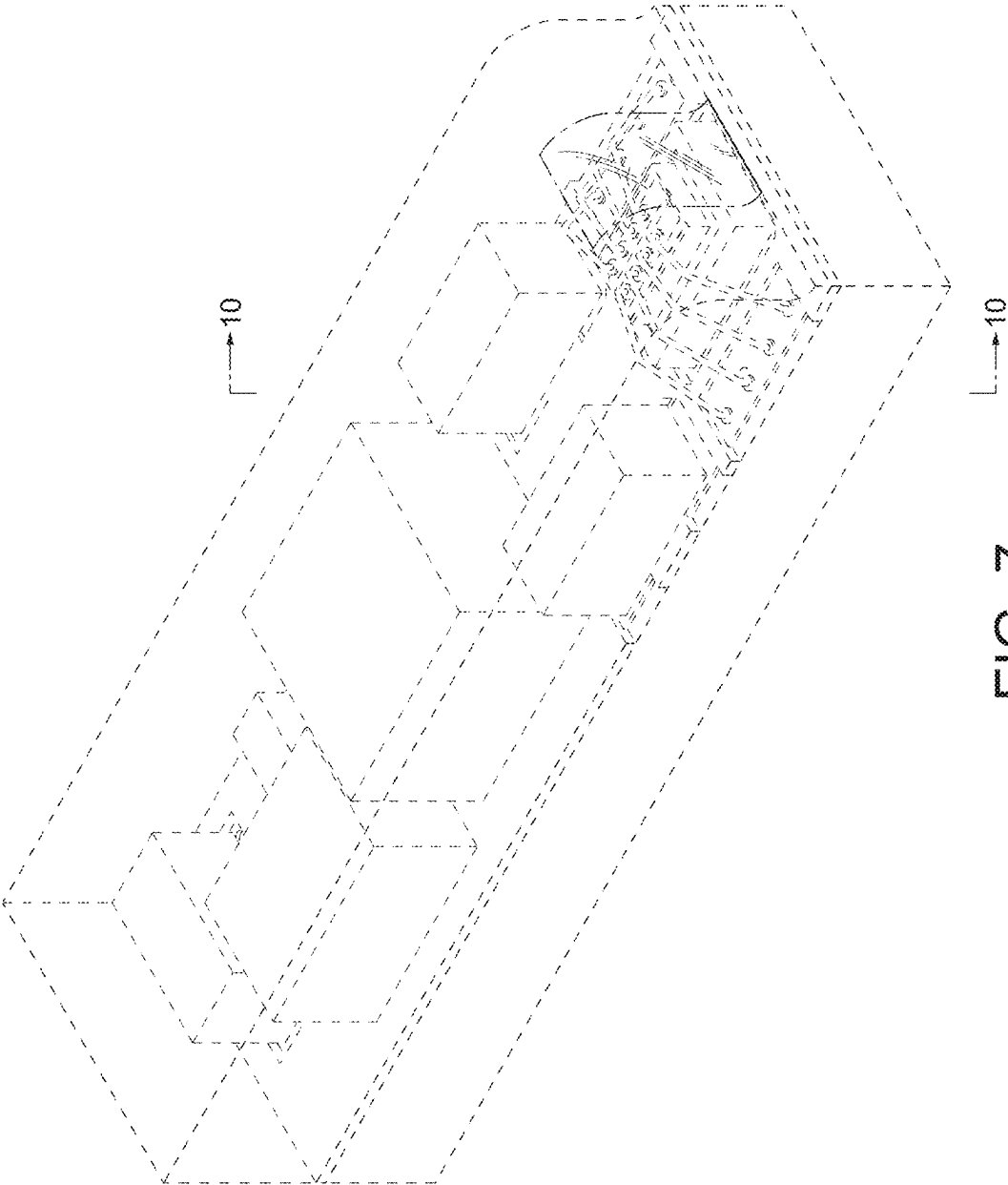


FIG. 7

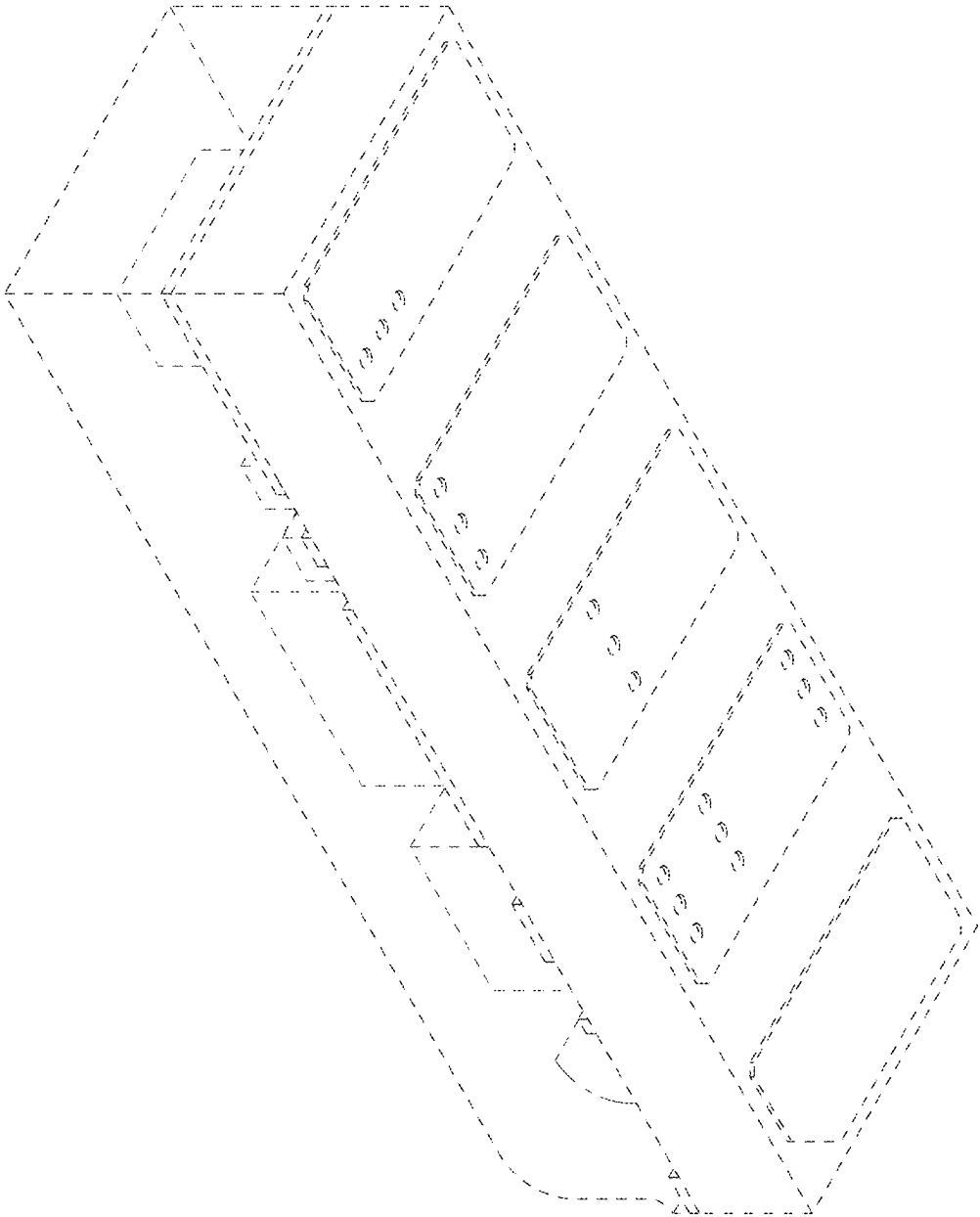


FIG. 8

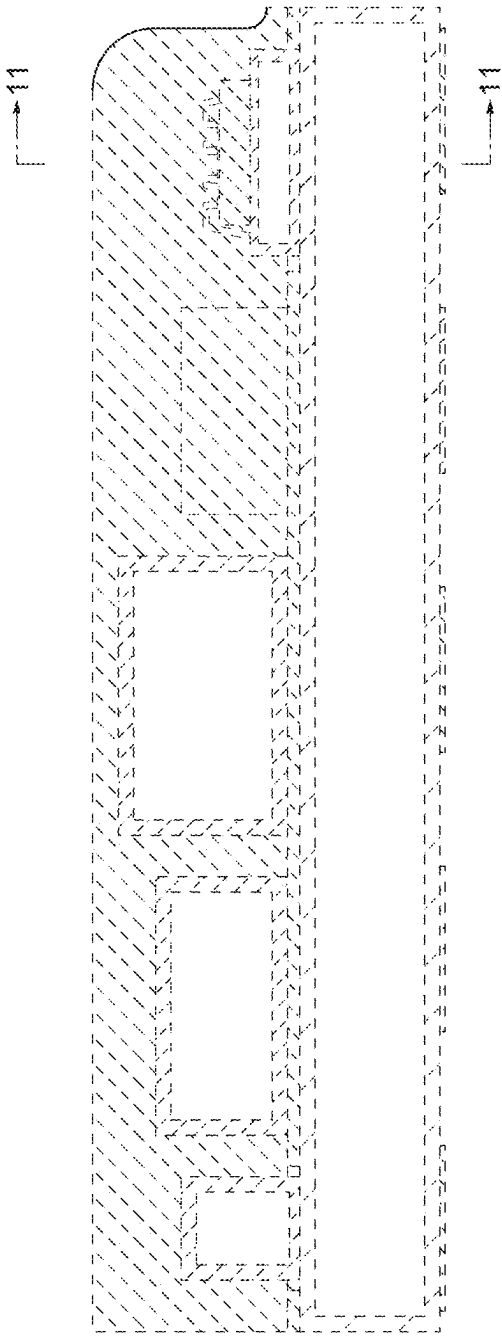


FIG. 9

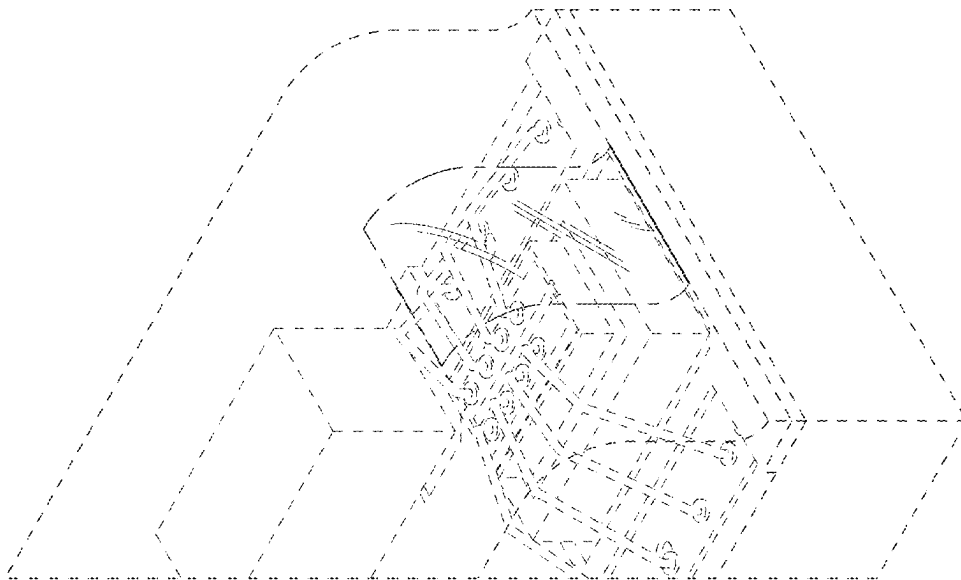


FIG. 10

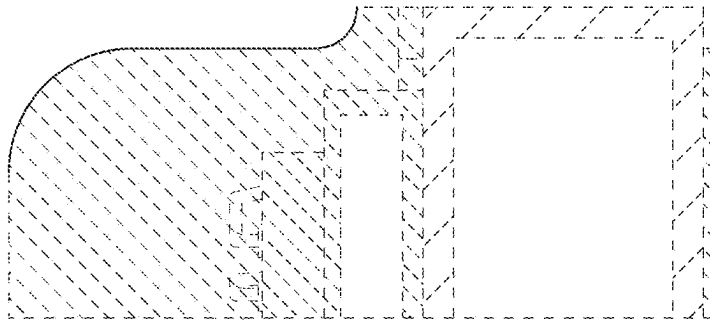


FIG. 11